PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hyung Soo Kim	12/02/2008
Yong Ju Kim	12/02/2008
Sung Woo Han	12/02/2008
Hee Woong Song	12/02/2008
Ic Su Oh	12/02/2008
Tae Jin Hwang	12/02/2008
Hae Rang Choi	12/02/2008
Ji Wang Lee	12/02/2008
Jae Min Jang	12/02/2008
Chang Kun Park	12/02/2008

RECEIVING PARTY DATA

Name:	Hynix Semiconductor, Inc.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Ichon-si
Internal Address:	Gyeonggi-do
City:	Ichon
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
Postal Code:	467-860

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12333194

CORRESPONDENCE DATA

Fax Number: (214)978-3099
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Email: nicole.m.otis@bakernet.com
Correspondent Name: Baker & McKenzie LLP
Address Line 1: 2001 Ross Ave.

Address Line 2: Suite 2300
Address Line 4: Dallas, TEXAS 75201

ATTORNEY DOCKET NUMBER:	95210324-200275
NAME OF SUBMITTER:	Noel C. Gillespie

Total Attachments: 5
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ASSIGNMENT

WHEREAS, I the undersigned inventor of residence as listed, have invented certain new and useful improvements as below entitled, for which an application for United States Letters Patent is made, said application having been designated as set forth below and filed on or about the date set forth below; and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"),

with an address of: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

desires to acquire the entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent(s) that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, continuations, continuations-in-part and extensions thereof; and I authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title and interest in and to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world, including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

I will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, I will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

Invention Name:	**SEMICONDUCTOR IC DEVICE HAVING POWER-SHARING AND METHOD OF POWER-SHARING THEREOF**
Serial No.:	12/333,194
Date Filed:	December 11, 2008

I hereby grant JOHN G. FLAIM, Registration No. 37,323, BRIAN C. McCORMACK, Registration No. 36,601, WILLIAM D. McSPADDEN, Registration No. 44,234, JAMES H. ORTEGA, Registration No. 50,554, RICHARD V. WELLS, Registration No. 53,757, HOWARD WISNIA, Registration No. 37,502, NOEL C. GILLESPIE, Registration No. 47,596, ROGER C. KUAN, Registration No. 56,558, KEVIN O'BRIEN, Registration No. 30,578, JAMES P. CONLEY, Registration No. 52,459, and all practitioners with the firm of Baker & McKenzie LLP (Customer Number 23562) with an office at 2001 Ross Avenue, Suite 2300, Dallas, TX 75201, the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned further declares that all statements made herein of his/her own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful and false statements may jeopardize the validity of the application or any patent issued thereon.

Signature of Inventor:	Hyungsoo Kim
Inventor(s) Name:	KIM, Hyung Soo
Residence:	San 136-1, Ami-ri, Bubal-eub, Ichon-si, Gyeonggi-do 467-860, Republic of Korea
Citizenship:	Korean
Date:	2008.12.2

Signature of Inventor: Yong Ju Kim

Inventor(s) Name: KIM, Yong Ju

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Han Sung Woo

Inventor(s) Name: HAN, Sung Woo

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Song HeeWoong

Inventor(s) Name: SONG, Hee Woong

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Icsu Oh

Inventor(s) Name: OH, Ic Su

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Hwang TaeJin

Inventor(s) Name: HWANG, Tae Jin

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Choi Haerang

Inventor(s) Name: CHOI, Hae Rang

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Lee Jiwang

Inventor(s) Name: LEE, Ji Wang

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Jaemin Jang

Inventor(s) Name: JANG, Jae Min

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2

Signature of Inventor: Changkun Park

Inventor(s) Name: PARK, Chang Kun

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2008.12.2
